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Interested committees:

Title: Draft BS IEC 63150-2 Ed.1.0 Semiconductor devices - Measurement and evaluation methods of kinetic energy harvesting devices under practical vibration environment. Part 2: Human arm swing motion.

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Introduction

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



47/2708/CD

COMMITTEE DRAFT (CD)

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IEC TC 47 : SEMICONDUCTOR DEVICES

SECRETARIAT:

Korea, Republic of

SECRETARY:

Mr Cheolung Cha

OF INTEREST TO THE FOLLOWING COMMITTEES:

PROPOSED HORIZONTAL STANDARD:

☐

Other TC/SCs are requested to indicate their interest, if any, in this CD to the secretary.

FUNCTIONS CONCERNED:

☐ EMC

☐ ENVIRONMENT

☐ QUALITY ASSURANCE

☐ SAFETY

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TITLE:

Semiconductor devices - Measurement and evaluation methods of kinetic energy harvesting devices under practical vibration environment - Part 2: Human arm swing motion

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

MEASUREMENT AND EVALUATION METHODS OF KINETIC ENERGY
HARVESTING DEVICES UNDER PRACTICAL VIBRATION ENVIRONMENT –

Part 2: Human arm swing motion

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IEC 63150-2 has been prepared by IEC technical committee TC47: Semiconductor Devices.

The text of this International Standard is based on the following documents:

Draft	Report on voting
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